

ADVANCED DIRECT IMAGING by ALTIX







DIRECT IMAGING WITH US

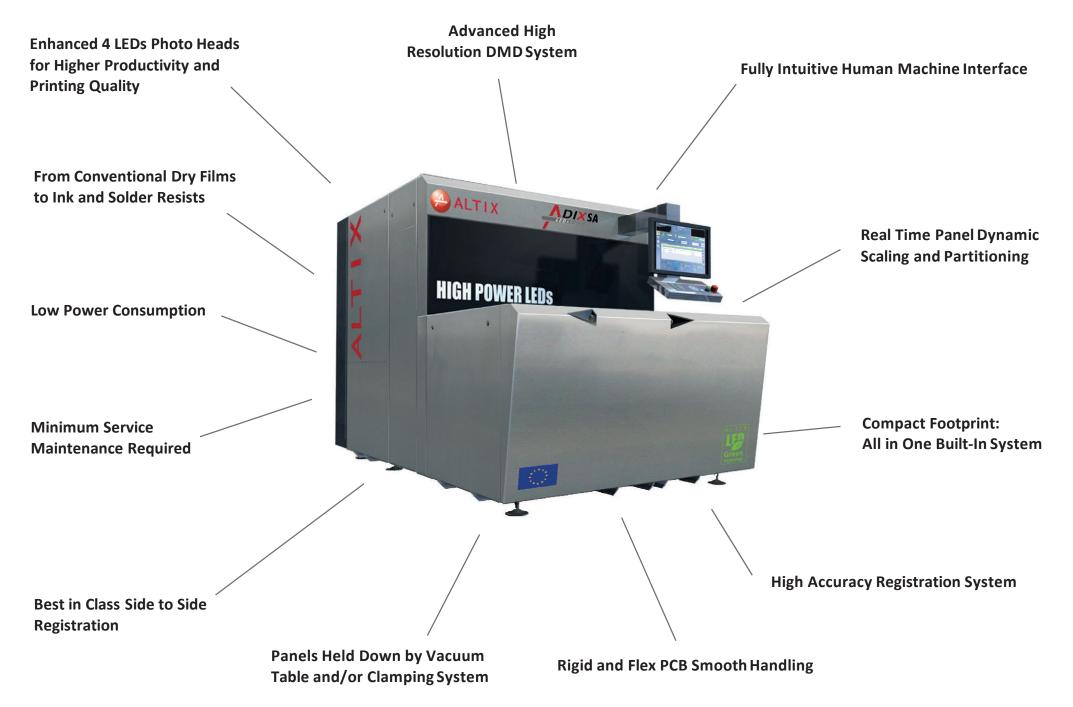
Direct Imaging Solution for PCB, FPCB, PCM (...)



Leiterplattentechnik / Industrievertretung



ADVANCED DIRECT IMAGING by ALTIX



ADIX Specifications

Panel	Panel size	From 228 x 254mm up to 610 x 762mm From 9"x10" up to 24"x30"		
	Panel thickness	0.04 to 6mm 1.6 to 236mils		
	Warp and twist	0.04 to 0.8mm 1.6 to 31mils × panel thickness: 1% of the diagonal 0.8 to 6mm 31 to 236mils × panel thickness: 0.5% of the diagonal		
	Weight	6kg max (13.22lbs)		
Web	Image size Web Thickness	From 190mm x 190mm (7.5"x7.5") up to 610mm x 685mm (24"x27") 0.030 to 0.5mm		
		Adix SA		Adix SA neo
Imaging	Resolution - L/S Resolution - DAM Edge Roughness Depth of Focus	10/10μm 0.4/0.4mil ⁽¹⁾ NA ± 0.5μm 100μm	20/20μm 0.8/0.8mil ⁽¹⁾ 25μm 1mil ± 1.5μm 200μm	30/30μm 1.2/1.2mils ⁽¹⁾ 50μm 2mils ± 3μm 400μm
	Autofocus Image to panel registration Side to side registration	± 8mm ± 315mils ± 8μm ± 0.31mil ± 12μm ± 0.47mil		
Throughput	Exposure time	14s with 30mJ/cm ² resist for 457 x 610mm (18"x 24") image size (6 heads) $^{(2)}$		
Process	Imaging resist materials Resist sensitivity Exposure spectrum Applications Production types	Conventional dry films or specific for DI ¤ Ink & solder resists From 10 to 1,250mJ/cm ² and above 4 wavelengths per Photo Head: 365/380/395/405nm PCB ¤ FPCB / Flex ¤ Photo Chemical Milling ¤ IC Substrate ¤ Touch Panel Inner Layers ¤ Outer Layers ¤ Soldermask (PSR)		
Graphic User Interface	Altix Direct Imaging Suite [™] Data Input	22 » touch screen, intuitive software, SPC capabilities, multilanguage Extended Gerber, ODB++, (others upon request)		
	Data Input	Extended Gerber, ODB++, (others upon request)		
General utilities & Foot print	Air supply Water supply Machine weight Dimensions	6 bars 1.5m ³ /min Water pressure 3~5 bars ¤ Flow rate: 23l/min @ 12°C or 33l/min @ 14°C 3,500kg (7,716lbs) L : 2,870mm (113") W: 1,750mm (69") H : 1,870mm (74")		

(1) depending on photoresist, surface preparation & DES process • (2) estimated time given as reference but can fluctuate according to the process adjustments

Imaging with us!

ADIX Semi-Automatic & Fully-Automatic Direct Imaging Product Range



Adix SA Semi-Automatic Panel to Panel DI Exposure

Semi-Automatic Direct Imaging solution for QTA, highmix low and medium volume production dedicated for all processes: Inner Layers, Outer Layers and Soldermask (PSR)



Adix CS / F Compact Standardized / Flip Compact - Island of Automation Fully Automatic Double Side

The system is designed to automatically load and unload panels into an Adix Direct Imaging system from either angular or slot cassettes.

An automatic flip & cleaning functions are integrated. The system is able to handle multiple batches and different panel sizes.

This compact automation is dedicated for all resists: dry film & solder resists and upgradable on site.



Adix SA neo Semi-Automatic Panel to Panel DI Exposure

Adix SA neo is the Fastest Imaging System with Customized Number of Photo Heads & Stripes. From 1 to 7 Photo Heads and upgradable on site. It is dedicated for all processes.



Adix PT / F Pass-Through / Flip In-Line Automation Fully Automatic Double Side

Integrated automation for fully-automatic Direct Imaging process in-line or island of automation.

Pass-through double-sided production with « in the air » flip.

This compact automation is dedicated fol all resists: dry film & solder resists and upgradable on site.



Adix RtR Roll to Roll DI Exposure Fully-Automatic

Adix Roll to Roll is a fully automatic Direct Imaging designed as a single sided Roll to Roll exposure system for fine line resolution, tight registration and high throughput capabilities.

It can handle all types of web for Flex Printed Circuit Boards, Photo Chemical Milling, Touch Panel, Thin Film Photovoltaic, etc...

ALDS-Power4+[™]

Advanced high power Leds with high resolution DMD System. The heart of the system is a creative combination of 4 highdensity LEDs light sources through a unique optical device coupled to a high frequency (up to 20kHz) DMD coordinated with a graphic signal and projectionlens.

This combination enables our ADIX solution to perform highresolution line and space down to 10µm.

ADIX Advanced Features



High Dynamic Autofocus Function

Highly precise and dynamic autofocus system is integrated inside each imaging head. The heads get real time feedbacks in order to take into account the warping and surface thickness variations of the board at ± 8 mm.

This state of the art tool plus the depth of focus of the head, which allows imaging in a consistently suitable state, drastically reduce the occurrence rate of imaging errors.

ALDS-Power4+[™]

Highly accurate real time scaling and distortion compensation technology responds to the PCB material variations. Each digital image can be scaled to match with the panel distortion.

For each panel, different scale factors can be applied with dynamic imaging modes: linear (Trapezoidal scaling, Orthogonal scaling) and non-linear (Polygonal scaling).

High Accuracy Registration

A multiple CCD cameras vision system enables featuring image to panel registration down to $\pm 8\mu$ m for high-end HDI designs.

Our solution can align the panel via a through hole or various alignment marks.

Our side-to-side registration for inner layers enables high accuracy alignment down to $\pm 12\mu m$ thanks to our exceptional registration system with adjustable points fitting the panel size.

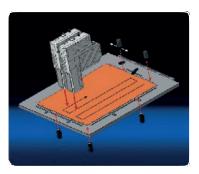
Smart Vacuum & Clamping Technology[™]

A unique Vacuum & Clamping mechanism offers an automatic selectable vacuum system.

Vacuum and clamping are automatically monitored according to the panel size.

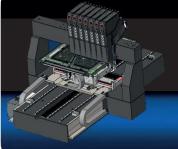
This clamping system can safely hold warped PCBs and handle panel thickness from 40um to 6mm.

In addition, with the autofocus function, it allows a perfect imaging compared to other systems having only a vacuum table without clamping mechanism.

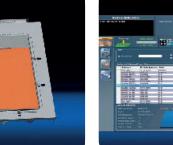


After alignment

Before correction



nm



Our powerful software "ALTIX Direct Imaging Suite™" offers more with multilingual capabilities and our statistical module "Altix Statistical Process Control Module".

The combination of different UV light wavelengths enables to polymerize a large range of dry film, ink and

Multi-Wavelenghts UV-LED

solder resists. With 4 LED wavelengths (365/380/395/405nm) and by adjusting the output ratio, it is possible to obtain the most efficient and fast printing for each type of dry resists or soldermask. UV-LED consumes less energy, generates less heat, and lasts much longer than typical laser diode

Number of Light Engines depending on your capacity. Upgradable on site

or blue laser based on light sources.

Our modular and flexible imaging technology ALDS-Power4[™] can be adapted to your throughput requirements. Also, the number of Photo Heads can be chosen accordingly when defining your new Direct Imaging equipment. This number of Photo Heads can be enlarged from 1 to 7 anytime in the future to match with your expanding needs.

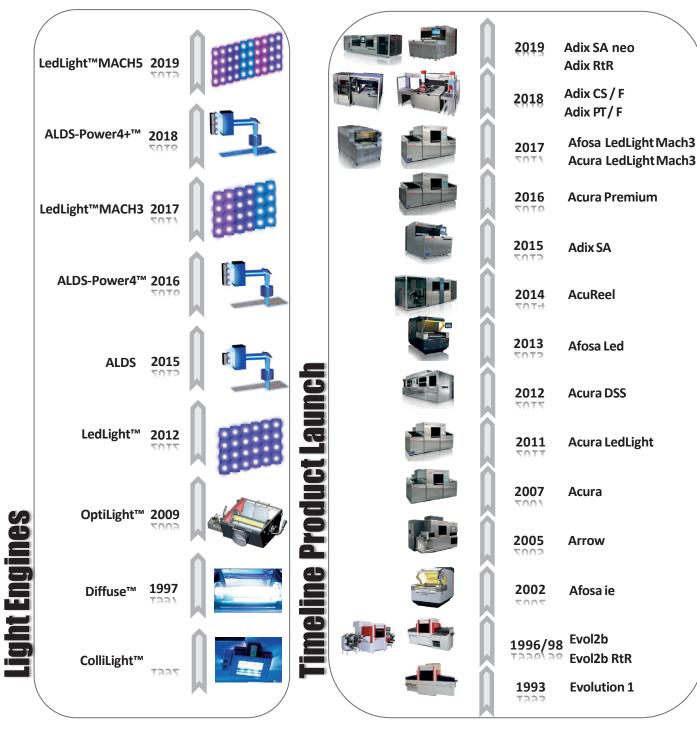
This incremental investment enables to have a fully optimized system, which means a quicker Return Of

Human Machine Interface (HMI)

Fully intuitive interface enables a friendly-user utilization for the operators. A state of the art touch screen graphical user interface enables an easy operating such as: guick job setups, parameters monitoring, full diagnosis, or process optimization.

Investment.

ALTIX, over **30** years of innovations and performances!







Imaging with us!



www.altix.fr www.kawa-gmbh.com